Email-Id: fardeenabdul317@gmail.com

Phone no: 9347514710

ABDUL.FARDEEN

CAREER OBJECTIVES:

To work enthusiastically in a challenging environment through skills and to improve my skills and also work for the growth of the Organization.

EDUCATION QUALIFICATION:

Name of the Course	Year	Name of the Institution	University/Board	GPA/Percentage
B-Tech	2021-2025	Sri Vasavi Institute of Engineering and Technology	JNTUK	6.5 GPA
Intermediate	2019-2021	Sri chaitanya junior college, Machilipatnam	State Board of Education	60%
SSC	2018-2019	St.vincent palloti school,pedana	State Board of Secondary Education	8.8 GPA

COURSES:

- had successfully completed 10 weeks of **Robotic Process Automation Virtual Internship** during December 2022- February - 2023.
- I had successfully completed 10 weeks of **Cyber Security Virtual Internship** during May to July - 2023**.**
- I had successfully completed 10 weeks of **Cloud Virtual Internship** during September to November - 2023.
- I had successfully completed 10 weeks of **Data Engineering Virtual Internship** during January to March - 2024.

EXTRA CURRICULAR ACTIVITIES:

- Prize in Quiz.

WEBINERS:

- I had participated in **Career Guidance Webinar** in collaboration with E-Cell IIT Hyderabad and Skill Dunia on 8/27/2023.

INTERNSHIPS/INDUSTRIAL VISITS:

- ⭕ I had successfully completed 10 weeks of **Cyber Security Virtual Internship** during May to July-2023.
- ⭕ Industrial visit to Andhra Pradesh Med Tech Zone (AMTZ) COMPANY in Vizag.

PERSONAL STRENGTHS:

- I am easily adapted to new environment.
- Good communication skills.
- Listening skills.
- I am punctual to my work**.**

PERSONAL INFORMATION:

Name : Abdul Fardeen

Father Name : Abdul Kalam

Mother Name : Sheerunissa begum

Date of Birth : 03-06-2002

Gender : Male

Languages Known : C , Python**.**

Permanent Address : near bus stand main road,

Sai nagar colony ,pedana-521366,   Krishna District,A.P

Hobbies : Watching&playing Cricket

DECLARATION :

I here by declare that the information above furnished is true and correct.

Place:

Date: **Signature**